

Application Note: Soldering Temperatures

Introduction

This application note applies to all of Littelfuse's products that are normally soldered to printed circuit boards (PCBs), including all reed switches. The primary materials making up these components are metal, glass, and thermoset plastic.

Recommendations

There are no unique requirements for soldering Littelfuse components compared to other common electrical components. The following general soldering recommendations apply to all except the DRR-DTH and DRT-DTH:

- Surface Mount Reflow: 20 seconds 260C max, 120 seconds max at >217C
- Wave Solder: 10 seconds 270C max.
- Hand/Rework Solder: 2 seconds 350C max.

For the DRR-DTH and DRT-DTH, when soldering to the double-wire end of the reed switch, a heat sink should be used between the reed switch and the soldering iron. Reed switches other than the MDRR-DT, DRR-DTH and DRT-DTH may be tinned or soldered in a solder pot without preheating. The glass may be allowed to contact the liquid solder. The MDRRDT may be tinned or soldered in a solder pot as long as the glass does not contact the solder.